

10-17-2002

FLH Ref. No.: 450101-03558



EET

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Patent and Trademark Office

To the Honorable Commissioner of

102251817

attached original documents or copy thereof.

1. Name of conveying party(ies)

Junichi REKIMOTO, Yuji AYATSUKA, Nobuyuki MATSUSHITA, Eduardo
A. SCIAMMARELLA, Haruo OBAAdditional name(s) of conveying party(ies) attached?
☐ Yes ☒ No

2. Name and address of receiving party(ies)

Name: SONY CORPORATION
7-35 Kitashinagawa 6-chome
Shinagawa-Ku, Tokyo 141-0001, JapanAdditional name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment
☐ Security Agreement
☐ Merger
☐ Change of Name
☐ OtherExecution Date: June 26, June 26, June 26, June 26 and July
3, 2002

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of
the application is:

A. USSN 10/168,637 (corresponding to Int'l Patent Application No.(s) PCT/JP01/09301 filed 23 October 2001)

Additional numbers attached? ☐ Yes ☒ No5. Name and address of party to whom correspondence
concerning document should be mailed:

Name: WILLIAM S. FROMMER

Internal Address: FROMMER LAWRENCE & HAUG LLP

Street Address: 745 FIFTH AVENUE

City: NEW YORK State: N.Y. Zip: 10151

6. Total number of applications and
patents involved

1

7. Total fee (37 CFR 3.41)

\$ 40.00

☒ Enclosed
☐ Authorized to be charged to
deposit account 50-0320

8. Deposit account number:

(Attach duplicate copy of this page if paying by deposit
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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true
copy of the original document.

Gordon Kessler

Name of Person Signing

Signature

October 7, 2002

Date

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Send comments regarding this burden estimate to the U.S. Patent and Trademark Office, Office of Information Systems,
PK2-1000C, Washington, D.C. 20231, and to the Office of Management and Budget, Paperwork Reduction Project (0651-0011),
Washington, D.C. 20503.

ASSIGNMENT

WHEREAS, I, an above named inventor, residing at the address(es) stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in:

INFORMATION PROCESSING APPARATUS AND INFORMATION PROCESSING METHOD HAVING COMMUNICATION FUNCTION

for which application for Letters Patent of the United States of America was made by me or by me and indicated next to my name and address;

AND WHEREAS, Daikin Industries, Ltd., a Japanese corporation, with offices at 1-1-1, Higashi-Shinjyoh-cho, Minami-ku, Tokyo 105-8555 Japan, hereinafter referred to as "DAIKIN", is a party having an interest in, and under said invention, said applicant, in disclosing the invention and in, to securing any best advantages or similar benefit and protection which may be obtained therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of one dollar (\$1.00), and the receipt and valuable consideration, the receipt and utility of which are hereby acknowledged, I, as a sole or joint inventor or as indicated herein, do hereby irrevocably assign, sell and transfer unto the said DAIKIN, its successors, assigns, and authorized licensees, the sole and entire right, title and interest in the said invention, said application, including any divisions and subdivisions thereof, and in and any and all Letters Patent of the United States, and subdivisions thereof, which may be obtained therefor in said country, and in and in any and all foreign countries, and in and under the international convention for the protection of industrial property, the American convention relating to patents, national and industrial design, and any other international agreements to which the United States of America adheres, and in and in the results arising in the future to be obtained in the filing of applications for patents or for industrial patents in the United States and in and in the results thereof, and hereby authorize and request the examination of patents to be taken in the United States Letters Patent to said DAIKIN, as the assignee of the whole right, title and interest thereof;

And I further agree to execute all necessary and suitable and useful future documents, including assignments in favor of DAIKIN or its assignees, as ASSIGNEE or its assignees, and any and all representatives may from time to time present to me and without further remuneration, in order to perfect title in said invention, in said country, and improvements in said invention, application and subdivisions thereof in the United States and in and in foreign countries;

And I further agree to properly execute and deliver and without further remuneration, such requests or declarations and law of papers for application for foreign patents, for filing subdivisions of said application for patent, and/or, for obtaining any release or relinquishment of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at his own expense;

And I further agree that DAIKIN will, upon its request, be provided to me with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: International Serial Number: PCT/JP01/09301, International Filing Date: 23 October 2001.

This assignment executed on the dates indicated below.

Daikin Industries

Name of first or sole inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of first or sole inventor

Signature of first or sole inventor

Date of this assignment

Yuji AYATSUKA

Name of second inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of second inventor

Signature of second inventor

Date of this assignment

Rei-kyu-ji HATSUMURA

Name of third inventor

Examination date of U.S. Patent Application

Kanagawa, Japan

Residence of third inventor

Signature of third inventor

Muneki Motokait 26 June 2002

Date of this assignment

Kunio A. Shimomura

Name of fourth inventor

Examination date of U.S. Patent Application

Osaka, Japan

Residence of fourth inventor

Signature of fourth inventor

Date of this assignment

Name of fifth

Name of fifth inventor

Examination date of U.S. Patent Application

Kanagawa, Japan

Residence of fifth inventor

Signature of fifth inventor

Yasuo Oka 03 July, 2002

Date of this assignment

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

INFORMATION PROCESSING APPARATUS AND INFORMATION PROCESSING METHOD HAVING COMMUNICATION FUNCTION

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 7-35, Kitashinagawa 6-chome, Shinagawa-ku, Tokyo 141-0001 Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: International Serial Number: PCT/JP01/09301, International Filing Date: 23 October 2001.

This assignment executed on the dates indicated below.

Junichi REKIMOTO

| | |
|--------------------------------|---|
| Name of first or sole inventor | Execution date of U.S. Patent Application |
| Tokyo, Japan | |

Residence of first or sole inventor

| | |
|-------------------------------------|-------------------------|
| Signature of first or sole inventor | Date of this assignment |
|-------------------------------------|-------------------------|

Yuji AYATSUKA

| | |
|-------------------------|---|
| Name of second inventor | Execution date of U.S. Patent Application |
| Tokyo, Japan | |

Residence of second inventor

| | |
|------------------------------|-------------------------|
| Signature of second inventor | Date of this assignment |
|------------------------------|-------------------------|

Nobuyuki MATSUSHITA

Name of third inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of third inventor

Signature of third inventor

Date of this assignment

Eduardo A. Sciammarella

Name of fourth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of fourth inventor

Signature of fourth inventor

Date of this assignment

6-26-82

Haruo OBA

Name of fifth inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of fifth inventor

Signature of fifth inventor

Date of this assignment